

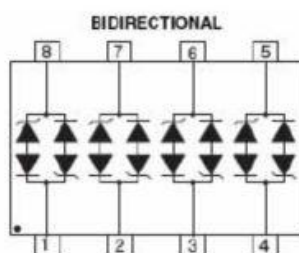
SMDA03LCC THRU SMDA24LCC TVS ARRAY SERIES



Description

The SMDAXLCC series of TVS array have been designed to provide bidirectional protection for sensitive electronics from damage due to voltage transients caused by electrostatic discharge (ESD), electrical fast transients (EFT), lightning and other voltage-induced transient events. The device can be used to protect combinations of four bidirectional lines.

Schematic & Pin Configuration



Features

- Protects 3.3, 5, 12, 15, 24 V Components
- Bidirectional
- Provides Electrically Isolated Protection
- 300 W @ 8/20 us
- Protects 4 Lines
- SO-8 Packaging
- LOW CAPACITANCE: 5PF
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Mechanical Characteristics

- SO-8 Surface Mount Package
- Approximate Weight: 0.1 grams
- PIN #1 Indicator: DOT on top of package
- Packaging: Tubes or Tape & Reel per EIA Standard 481

Application

- RS-232 & RS-422 data lines
- Microprocessor Based Equipment
- Notebooks, Desktops, & Servers
- LAN/WAN Equipment
- Serial and Parallel Port
- Peripherals

Absolute Maximum Ratings:

Parameter	Symbol	Value	Units
Peak Pulse Power, 8/20 μ s Wave shape	P	300	W
Operating Temperature	T _J	-55 to +125	°C
Storage Temperature	T _{stg}	-55 to +150	°C
Lead Soldering Temperature	T _L	260 (10 Sec.)	°C

Electrical Characteristics@25°C

Part Number	Stand-off Voltage V_{wm} (V) Max	Breakdown Voltage V_{BR} @1mA (V) Min	Clamping Voltage V_c @ 1 A (V) Max	Leakage Current I_R @ V_{wm} (uA) Max	Capacitance (f = 1MHz) C @ 0V (pF) Max	Temperature Coefficient of V_{BR} a(V_{BR}) mv/°C Max
SMDA03LCC	3.3	4	7	200	15	-5
SMDA05LCC	5.0	6	9.8	20	15	1
SMDA12LCC	12.0	13.3	19	1	15	8
SMDA15LCC	15.0	16.7	24	1	15	11
SMDA24LCC	24.0	26.7	43	1	15	28

Ratings and Characteristics Curves

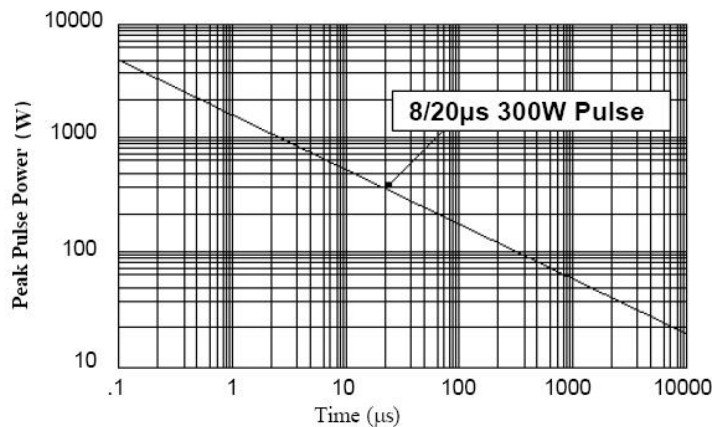


Figure 1. Peak Pulse Power Vs Pulse Time (µs)

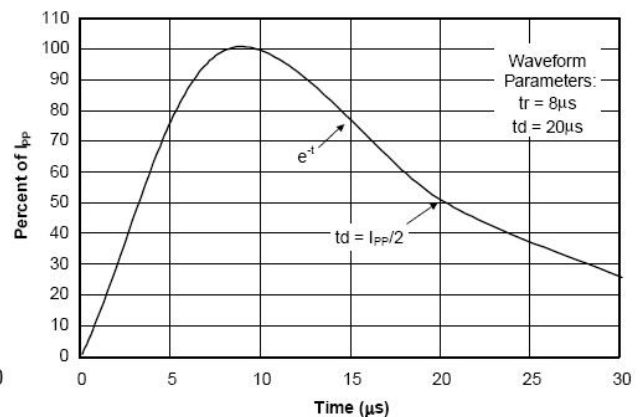


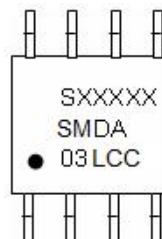
Figure 2. Pulse Wave Form

Ordering Information

Device	Package	Shipping
SMDA03LCC THRU SMDA24LCC	SO-8 (Pb-Free)	2500pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



Where XXXXX is YYWWL

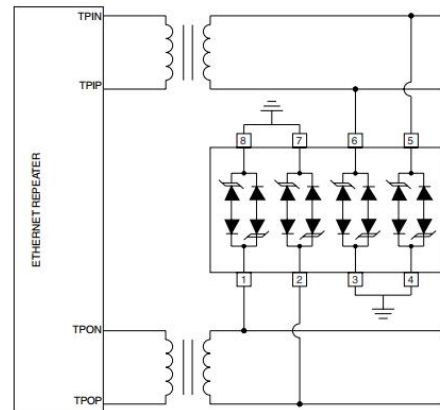
SMDA03LCC = Part Number
S = S
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin

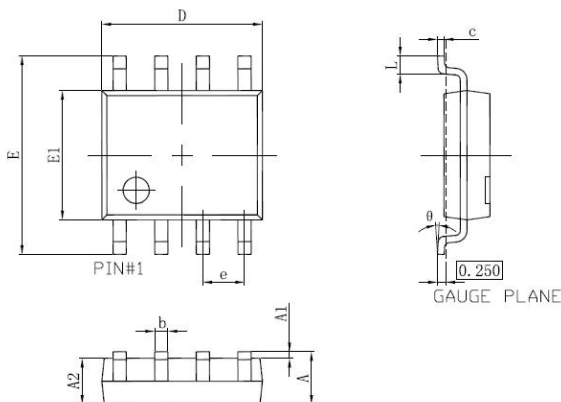
Circuit Diagram

Ideal for Ethernet applications, SMDAxxLCC Series provides up to four (4) lines of protection in a common-mode configuration. Circuit connectivity is as follows:

- ✓ TPIN is connected to Pin 5.
- ✓ TPIP is connected to Pin 6.
- ✓ TPON is connected to Pin 1.
- ✓ TPOP is connected to Pin 2.
- ✓ Pins 3, 4, 7 & 8 are connected to ground.

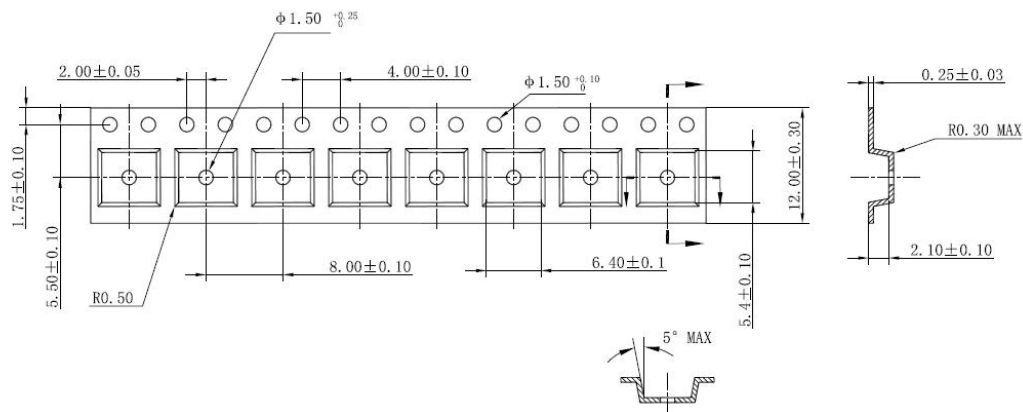


Mechanical Dimensions SO-8



SYMBOL	Millimeters		Inches	
	MIN.	MAX.	MIN.	MAX.
A	1.350	1.800	0.053	0.071
A1	0.100	0.250	0.004	0.010
A2	1.350	1.750	0.053	0.069
b	0.306	0.510	0.012	0.020
c	0.150	0.300	0.006	0.012
D	4.720	5.120	0.186	0.202
e	1.140	1.400	0.045	0.055
E	5.700	6.300	0.224	0.248
E1	3.750	4.150	0.148	0.163
L	0.300	1.270	0.012	0.050
θ	0°	8°	0°	8°

Carrier Tape Specification SO-8





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